Product Datasheet

C3535X-FNxx Series
High Power Infrared LED

Introduction

The C3535X-FNxx LED from TSLC brings industry leading technology to the infrared applications market with its high reliability and performance. With a ceramic substrate and a 140/100/65 degree view angle primary lens, the C3535X-FNxx LED is a perfect solution for horticulture, security cameras, surveillance systems, machine vision and general purpose IR applications.

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RoHS Compliant

Characteristics

Absolute Maximum Ratings (Tj = 25°C)

Parameter	Rating
	IR Series
DC Forward Current (mA)	1000mA
LED Junction Temperature	115℃
LED Operating Temperature	-40℃~85℃
Storage Temperature	-40℃~115℃
Soldering Temperature	Max. 260℃ / Max. 10sec. (JEDEC 020)
ESD Sensitivity	2,000 V HBM (JESD-22A-114-B)
Reverse Voltage	Not designed to be driven in reverse bias (VR≦5V)
Preconditioning	Acc. to JEDEC Level 1

Product Name

C 3535 X - FN x x

1 2~5 6 7~8 9 10

Code 1: Substrate composition, C: Ceramic Al_2O_3

Code 2.3.4.5: Package size, 3535: 3.5*3.5mm

Code 6: X: Product Class, IR (>700nm)

Code 7.8: Wavelength Class, FN: IR (720~750nm)

Code 9: Lens type, L: 140 degree, A: 100 degree, F: 65 degree

Code 10: Internal code

General Characteristics at 700mA

Part number	Color	Peak Wavelength λp		$2\theta_{1/2}$	Temperature Coefficient of Vf (mV/˚C)	Thermal Resistance Junction to Pad
		Min	Max		ΔVF /ΔTJ	(˚C/W) $R\Theta_{J-L}$
C3535X-FNLx	Fx0	720	750	140	-2~-4	10
C3535X-FNAx	Fx0	720	750	100	-2~-4	10
C3535X-FNFx	Fx0	720	750	65	-2~-4	10

Notes:

1. The peak wavelength is measured with an accuracy of ±1nm
2. All values stated are subject to the limits and set up of TSLC's testers. All other measurement data are defined as long-term production mean values and are only given for reference.
3. A critical component is a component used in a life-support device or system whose failure can reasonably be expected to cause the failure of that life-support device or system, or to affect its safety or effectiveness of that device or system. Life support devices or systems are intended (i) to be implanted in the human body, or (ii) to support and/or maintain and sustain human life. If they fail, it is reasonable to assume that the health of the user may be endangered. Components used as a critical component must be approved in writing by TSLC Corporation.

Radiometric Power and Forward Voltage (Tj = 25°C)

Part Number	Color	Performance at Test Current (700mA)					Performance at 1000mA
		Group	Radiometric Power (mW)		VF		Calculated Minimum Radiometric Power* (mW)
			Min	Max	Min	Max	
C3535X-FNLx (beam angle 140°)	Fx0 (720-750nm)	NE1	400	440	1.6	3.0	540
		NE2	440	480	1.6	3.0	594
		NE3	480	520	1.6	3.0	648
		NE4	520	560	1.6	3.0	702
		NE5	560	600	1.6	3.0	756
		NF1	600	650	1.6	3.0	810
		NF2	650	700	1.6	3.0	878
		NF3	700	750	1.6	3.0	945
C3535X-FNAx (beam angle 100°)	Fx0 (720-750nm)	NE1	400	440	1.6	3.0	540
		NE2	440	480	1.6	3.0	594
		NE3	480	520	1.6	3.0	648
		NE4	520	560	1.6	3.0	702
		NE5	560	600	1.6	3.0	756
		NF1	600	650	1.6	3.0	810
		NF2	650	700	1.6	3.0	878
		NF3	700	750	1.6	3.0	945
C3535X-FNFx (beam angle 65°)	Fx0 (720-750nm)	NE1	400	440	1.6	3.0	540
		NE2	440	480	1.6	3.0	594
		NE3	480	520	1.6	3.0	648
		NE4	520	560	1.6	3.0	702
		NE5	560	600	1.6	3.0	756
		NF1	600	650	1.6	3.0	810
		NF2	650	700	1.6	3.0	878
		NF3	700	750	1.6	3.0	945

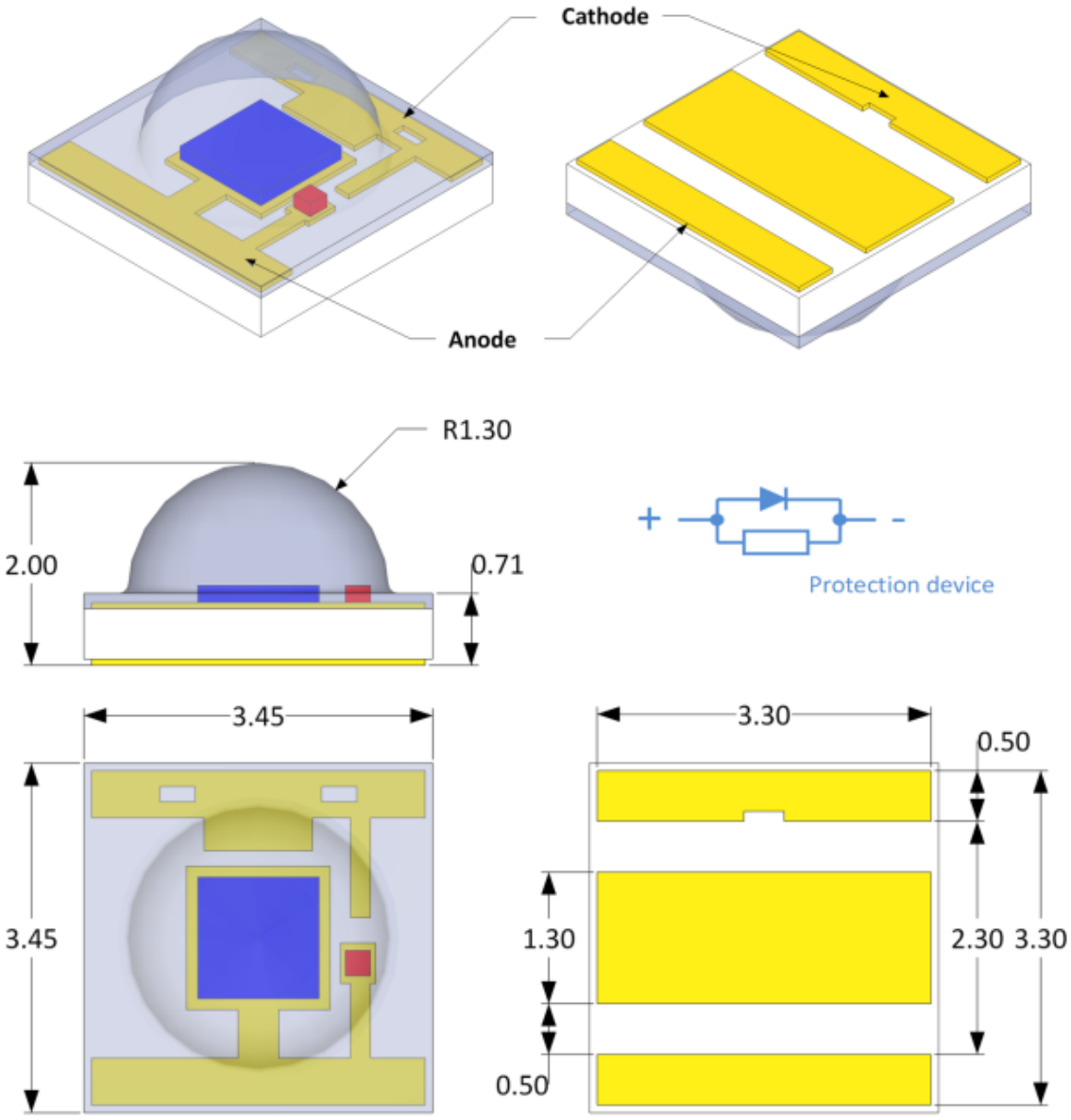
Note: 1. Radiometric power is measured with an accuracy of ±10%

2. The forward voltage is measured with an accuracy of ±0.2V

*Calculated values are for reference only.

Mechanical Dimensions

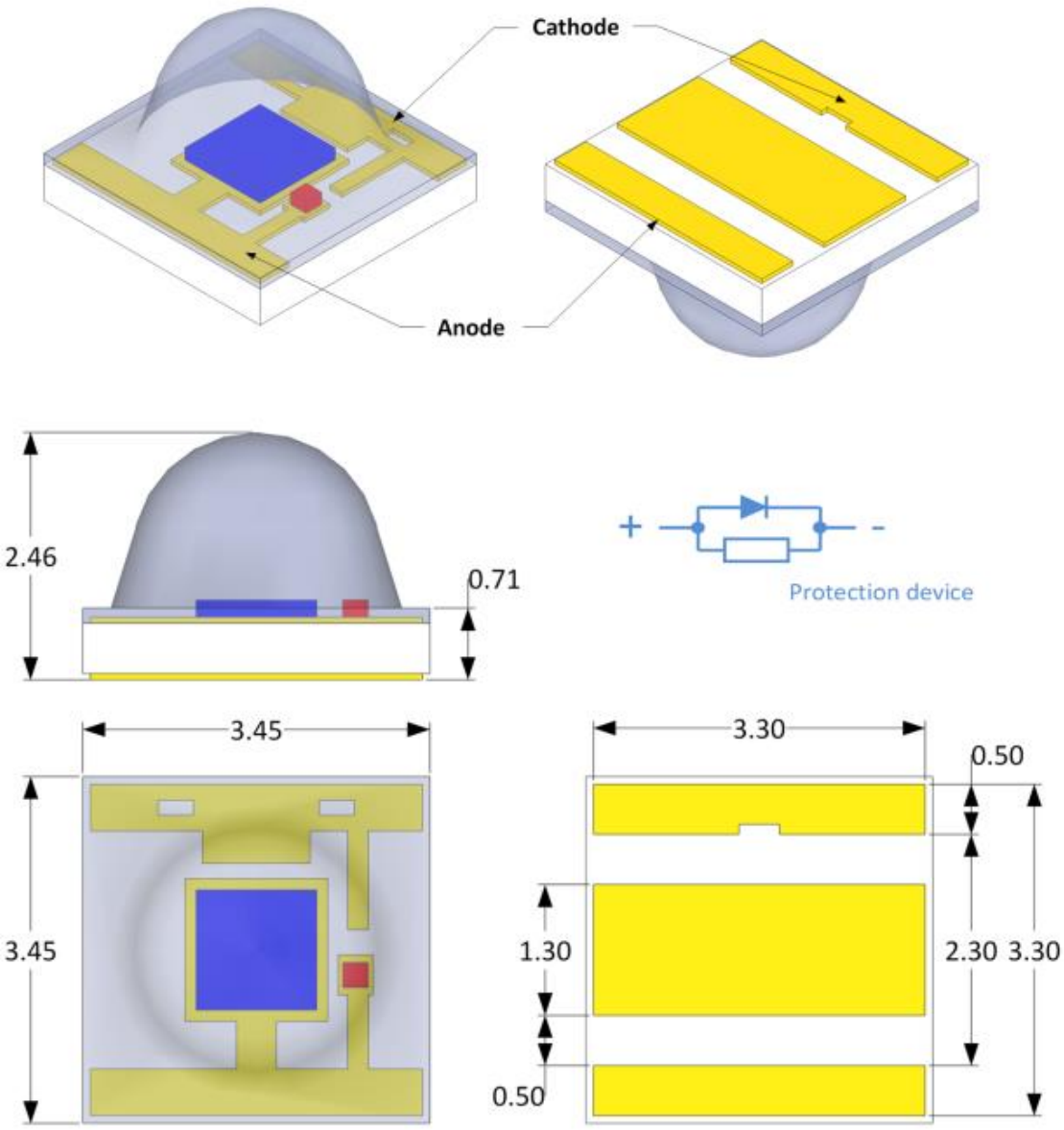
C3535X-FNLx (beam angle 140°)



Notes:

1. Drawing is not to scale
2. All dimensions are in millimeter
3. Dimensions are ±0.13mm unless otherwise indicated

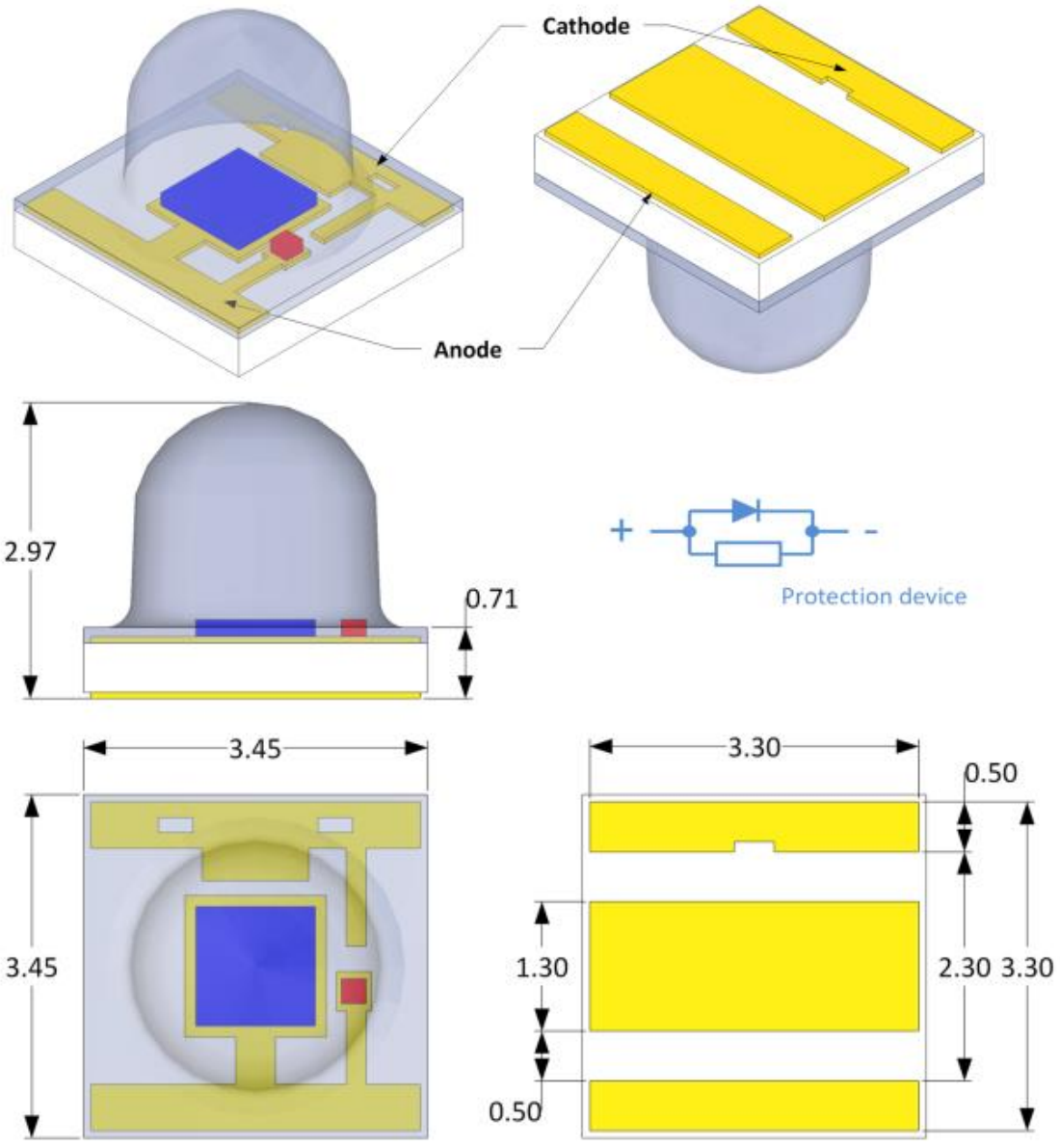
C3535X-FNAx (beam angle 100°)



Notes:

1. Drawing is not to scale
2. All dimensions are in millimeter
3. Dimensions are ±0.13mm unless otherwise indicated

C3535X-FNFx(beam angle 65°)

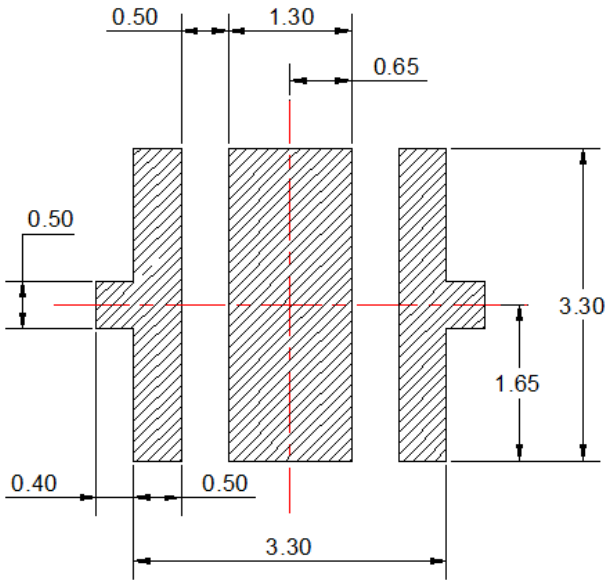


Notes:

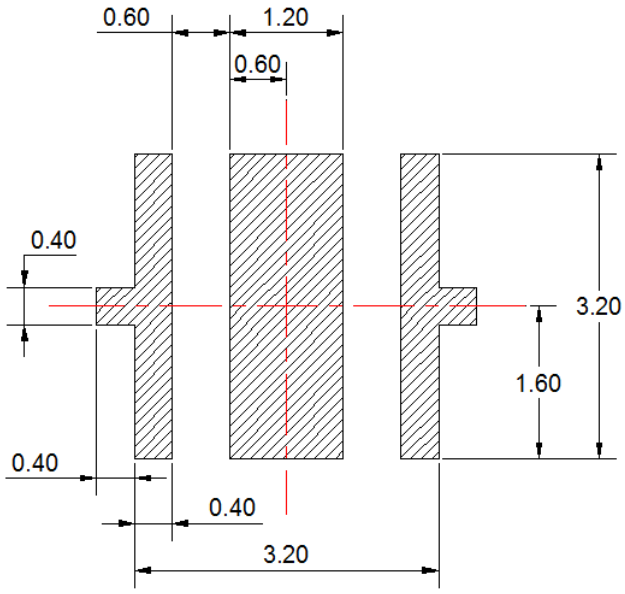
1. Drawing is not to scale
2. All dimensions are in millimeter
3. Dimensions are ±0.13mm unless otherwise indicated

Recommended Solder Pad Design

Recommended Soldering Pad Design



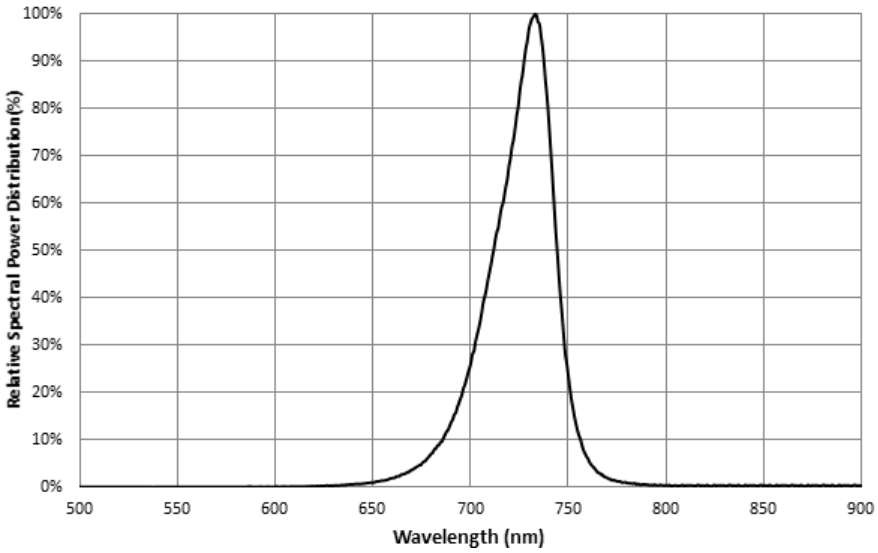
Recommended Stencil Pattern Design (Marked Area is Opening)



Notes :

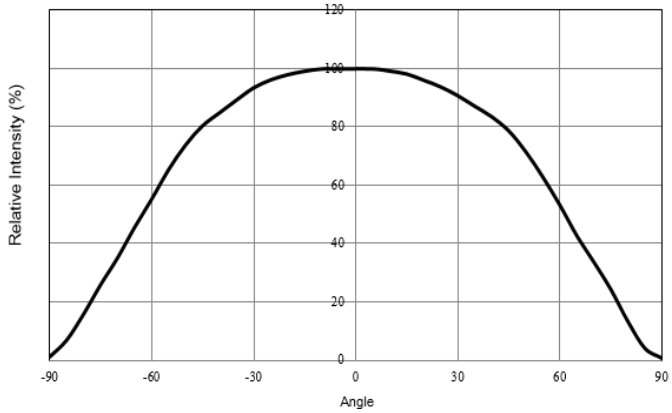
1. Drawing is not to scale
2. All dimensions are in millimeter

Relative Spectral Power Distribution, Tj=25°C

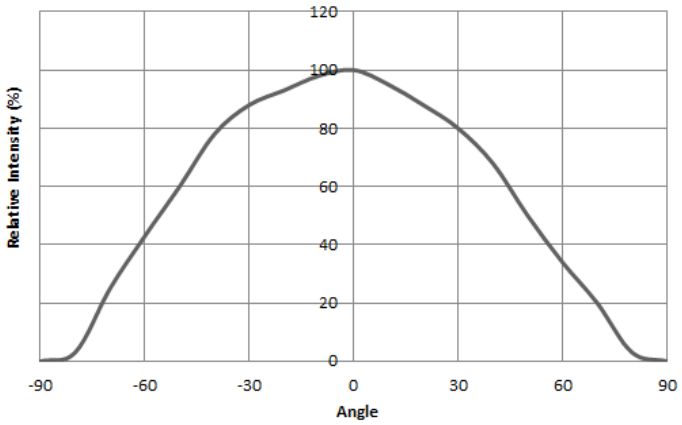


Typical Spatial Radiation Pattern

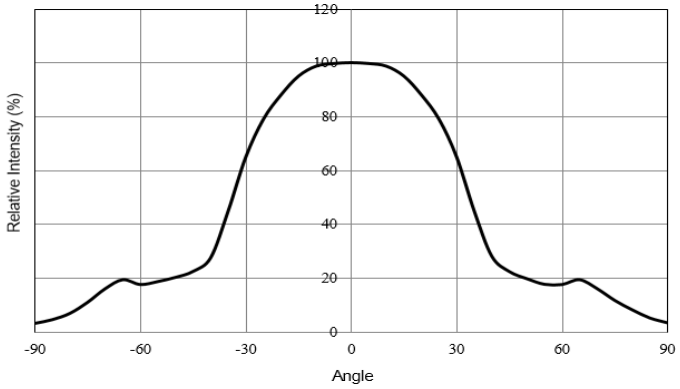
C3535X-FNLx (beam angle 140°)



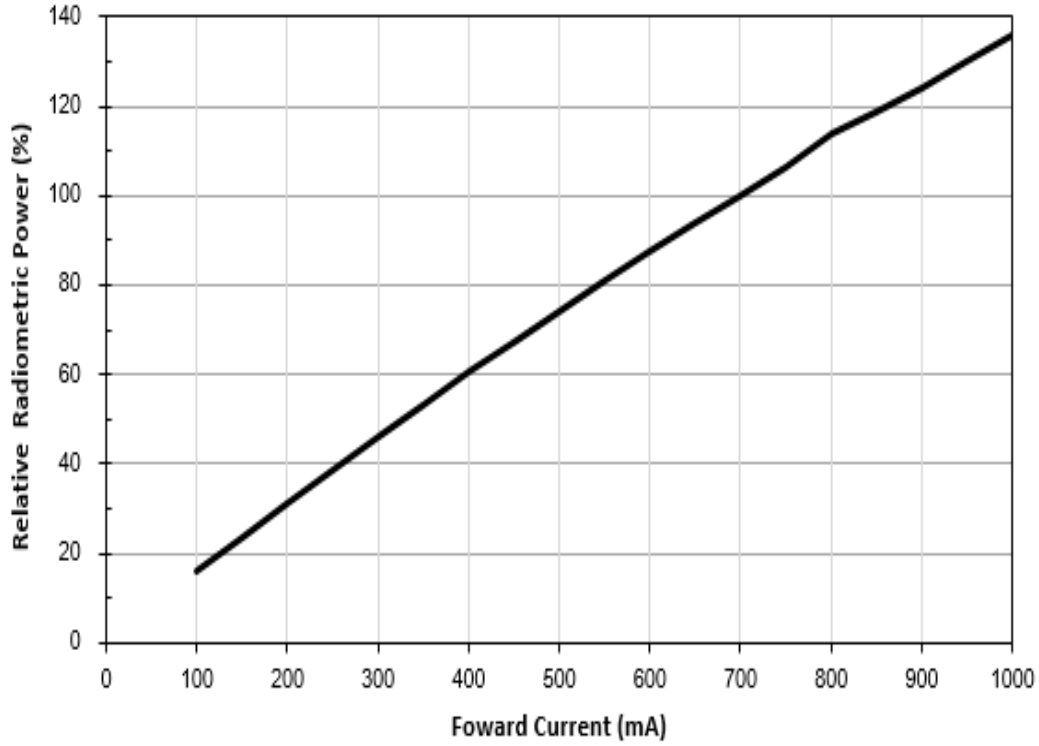
C3535X-FNAx (beam angle 100°)



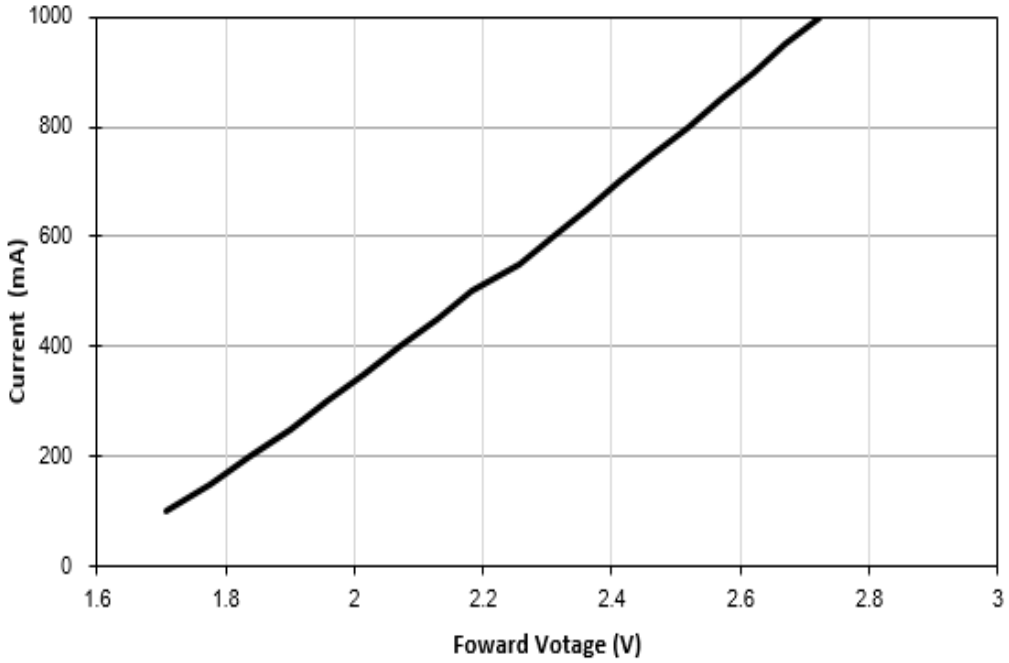
C3535X-FNFx (beam angle 65°)



Typical Forward L-I Characteristics, Tj=25˚C

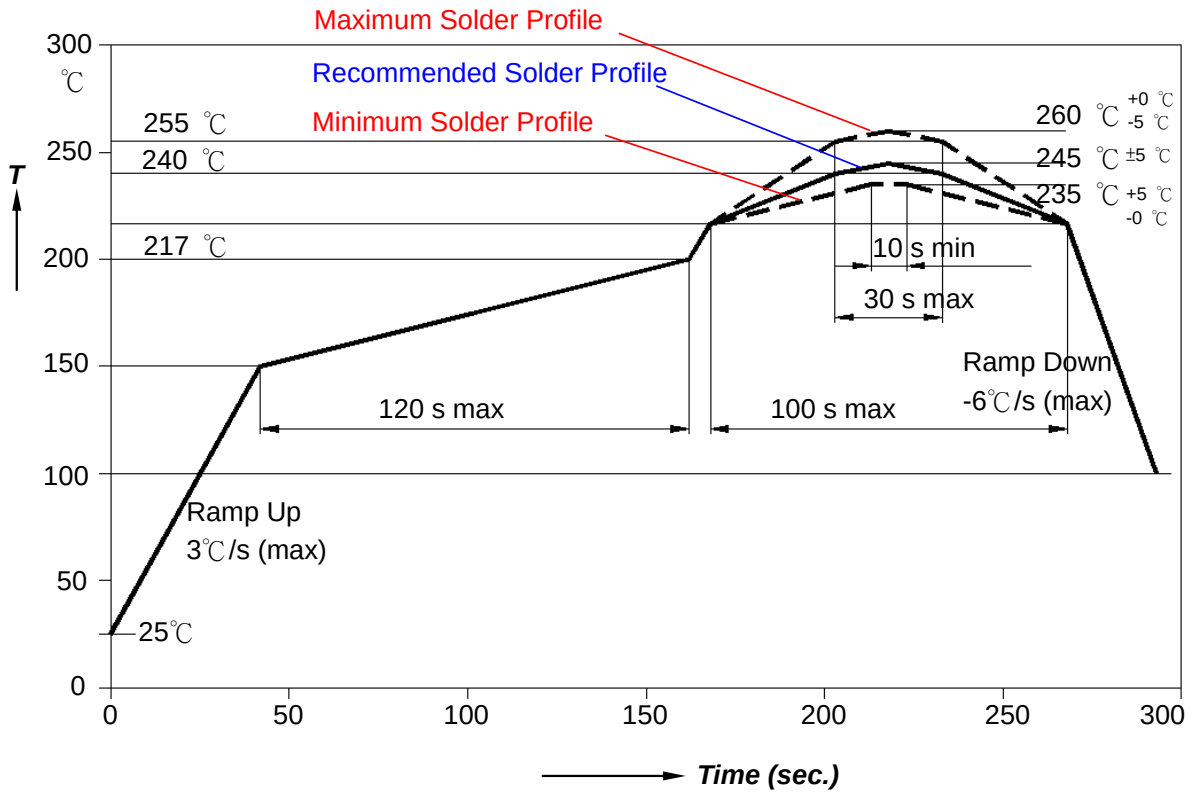


Typical Forward I-V Characteristics, Tj=25˚C



Recommended Soldering Profile

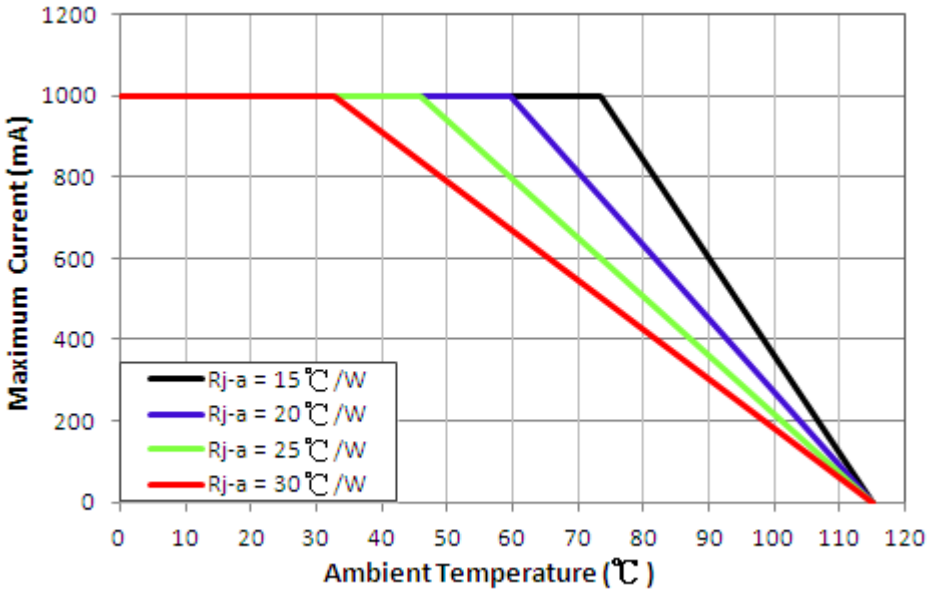
The LEDs can be soldered using the parameters listed below. As a general guideline, the users are suggested to follow the recommended soldering profile provided by the manufacturer of the solder paste. Although the recommended soldering conditions are specified in the list, reflow soldering at the lowest possible temperature is advised for the LEDs.



Profile Feature	Sn-Pb Eutectic Assembly	Pb-Free Assembly
Average Ramp-up Rate (Ts_{max} to Tp)	3˚C /second max.	3˚C /second max.
Preheat - Temperature Min(Ts_{min}) - Temperature Max(Ts_{max}) - Time(ts_{min} to ts_{max})	 100˚C 150˚C 60-120 seconds	 150˚C 200˚C 60-180 seconds
Time maintained above: - Temperature(T_L) - Time(t_L)	 183˚C 60-150 seconds	 217˚C 60-150 seconds
Peak/classification Temperature(Tp)	215˚C	260˚C
Time within 5˚C of actual Peak Temperature(tp)	10-30 seconds	20-40 seconds
Ramp-Down Rate	6˚C /second max.	6˚C /second max.
Time 25˚C to Peak Temperature	6 minutes max.	8 minutes max.

Thermal Design

Thermal design of the end product is important. The thermal resistance between the junction and the solder point ($R\Theta_{J-P}$) and the end product should be designed to minimize the thermal resistance from the solder point to ambient in order to optimize the emitter life and optical characteristics. The maximum operation current is determined by the plot of Allowable Forward Current vs. Ambient Temperature.



The junction temperature can be correlated to the thermal resistance between the junction and ambient (Rja) by the following equation.

$$Tj=Ta + Rja*W$$

Tj: LED junction temperature

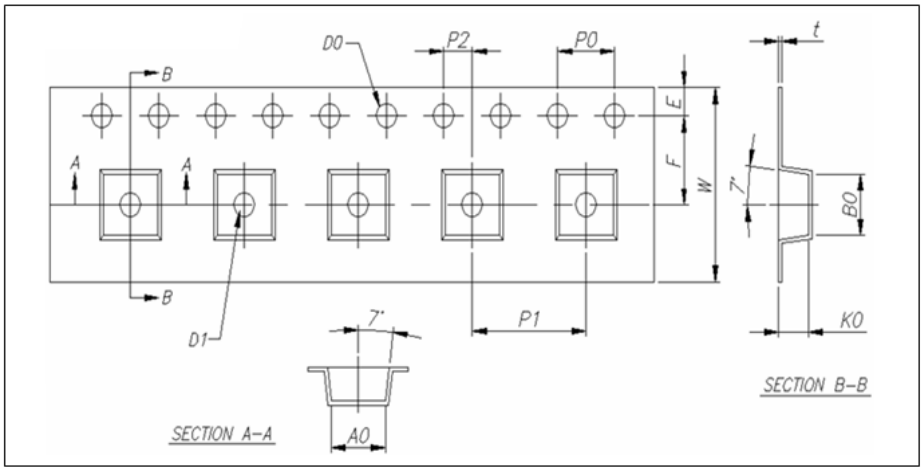
Ta: Ambient temperature

Rja: Thermal resistance between the junction and ambient

W: Input power (I_F*V_F)

Packing Information

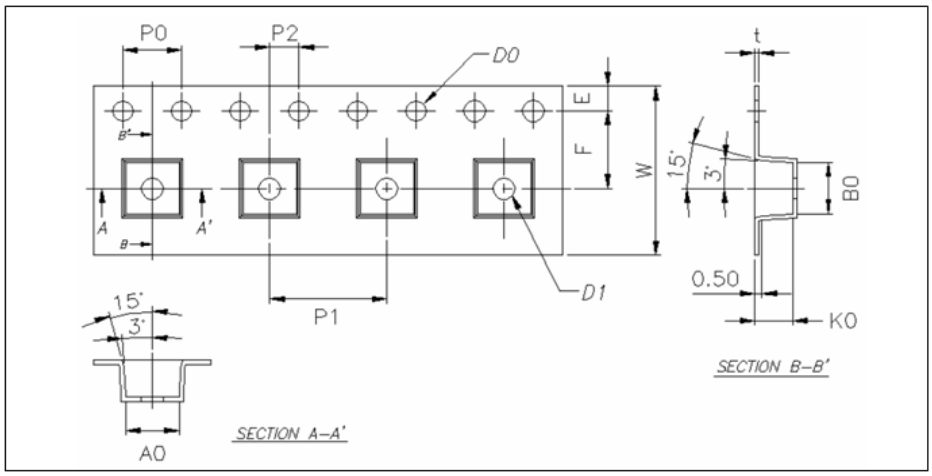
C3535X-FNLx series, Max QTY: 1000ea / roll



Item	Specification	Tol.(+/-)
W	12.00	±0.20
E	1.75	±0.10
F	5.50	±0.05
D0	1.50	+0.10, -0
D1	1.50	±0.10
P0	4.00	±0.10
P1	8.00	±0.10
P2	2.00	±0.10
P0X10	40.00	±0.20

Item	Specification	Tol.(+/-)
t	0.25	±0.05
A0	3.80	±0.10
B0	3.80	±0.10
K0	2.20	±0.10

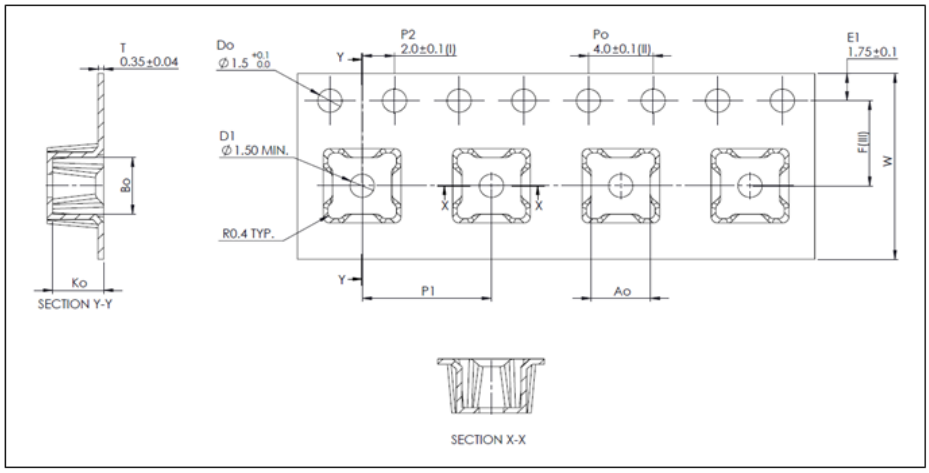
C3535X-FNAx series, Max QTY: 500ea / roll



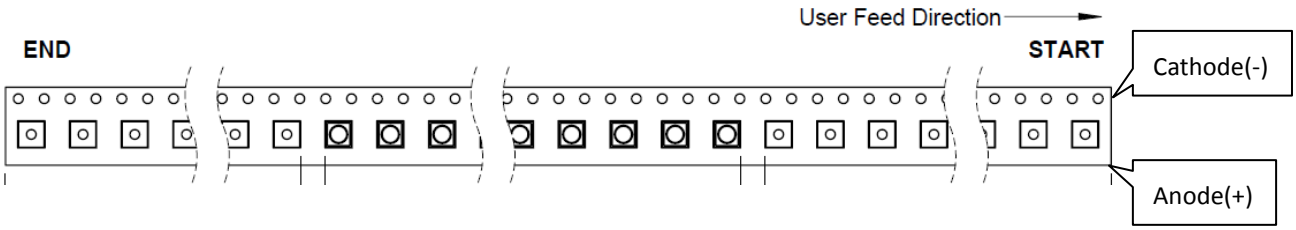
Item	Specification	Tol.(+/-)
W	12.00	±0.30
E	1.75	±0.10
F	5.50	±0.05
D0	1.50	+0.10, -0
D1	1.50	+0.10, -0
P0	4.00	±0.10
P1	8.00	±0.10
P2	2.00	±0.05
P0X10	40.00	±0.20

Item	Specification	Tol.(+/-)
t	0.30	±0.05
A0	3.65	±0.10
B0	3.65	±0.10
K0	2.56	±0.10

C3535X-FNFx series, Max QTY: 500ea / roll



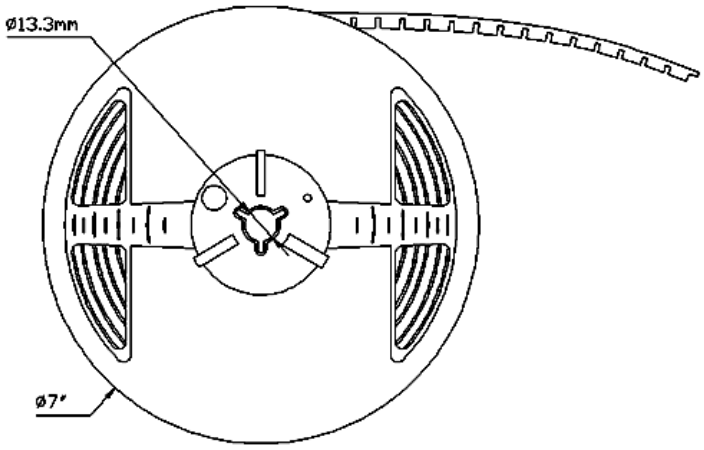
Item	Specification	Tol.(+/-)
A0	3.65	±0.10
B0	3.65	±0.10
K0	3.15	±0.10
F	5.50	±0.10
P1	8.00	±0.10
W	12.00	±0.30



Trailer 160mm (min) of empty pockets sealed with tape

Loaded Pockets

Leader 400mm (min) of empty pockets sealed with tape



Note:

All dimensions are in millimeter.

About Us

TSLC Corporation is devoted to developing high-density and multi-size emitters with powerful output to satisfy the needs of every customer.

TSLC Corporation is the leader in LED solutions. Unlimited design flexibility for interior and exterior spaces with high-end lighting effect; energy-efficient for UV curing to improve the quality of medical care; horticulture solutions create a better environment for everyone; high-intensity rotatable lightings for the entertainment industry, TSLC is always there for your lighting needs.

For further company or product information, please visit us at **www.tslc.com.tw** or please contact **sales@ tslc.com.tw.**

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